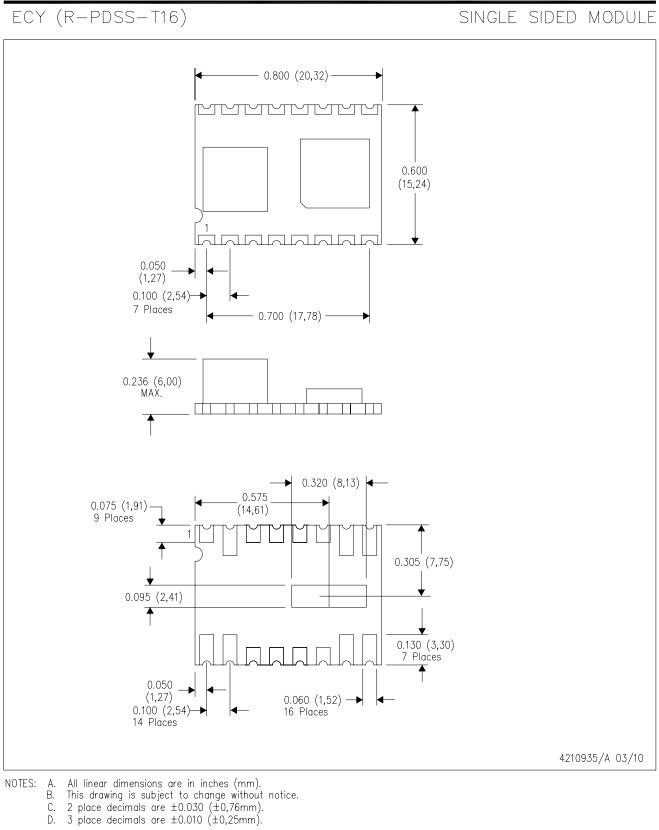
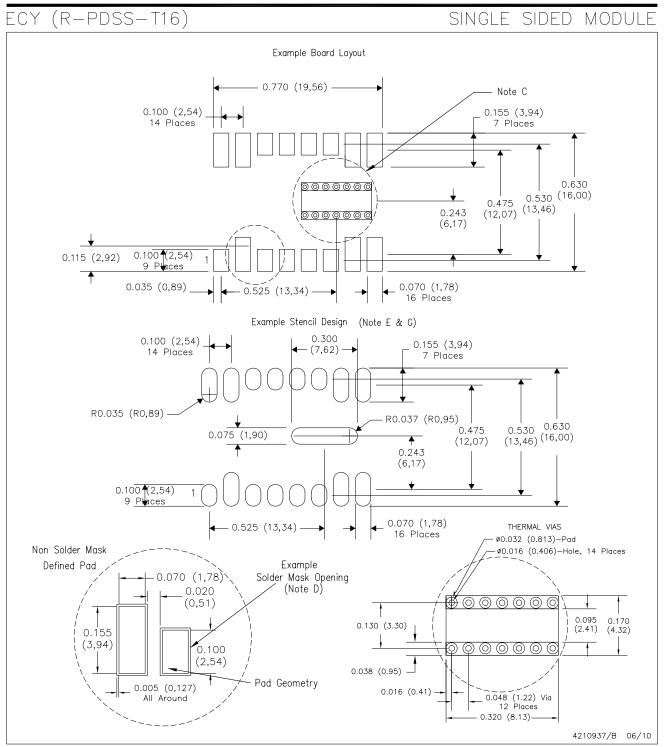
MECHANICAL DATA





LAND PATTERN



NOTES: A. All linear dimensions are in inches & millimeters.

- В. С.
- This drawing is subject to change without notice. This package is designed to be soldered to a thermal pad on the board. This pad must be at ground potential and be connected to an internal ground plane with multiple thermal vias.
- D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should Ε.
- contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations. Paste screen thickness: 0.006 (0,15). 3 place decimals are ±0.010 (±0.25) E.
- G.



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